



## Material Content Data Sheet



<b>Sales Product Name</b>		IPG16N10S4-61A		<b>Issued</b>		1. August 2018			
<b>MA#</b>		MA001658284							
<b>Package</b>		PG-TDSON-8-10		<b>Weight*</b>		98.16 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.384	1.41	1.41	14098	14098	
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		142		
	non noble metal	iron	7439-89-6	0.046	0.05		473		
	non noble metal	copper	7440-50-8	46.380	47.26	47.32	472478	473093	
	non noble metal	aluminium	7429-90-5	0.732	0.75	0.75	7457	7457	
wire	non noble metal	aluminium	7429-90-5	0.732	0.75	0.75	7457	7457	
encapsulation	organic material	carbon black	1333-86-4	0.091	0.09		930		
	plastics	epoxy resin	-	6.483	6.60		66039		
	inorganic material	silicondioxide	60676-86-0	39.078	39.81	46.50	398092	465061	
leadfinish	non noble metal	tin	7440-31-5	1.396	1.42	1.42	14225	14225	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		15		
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6144	6159	
solder	non noble metal	tin	7440-31-5	0.039	0.04		398		
	noble metal	silver	7440-22-4	0.049	0.05		498		
	non noble metal	lead	7439-92-1	1.866	1.90	1.99	19011	19907	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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